

2SD0662, 2SD0662B (2SD662, 2SD662B)

Silicon NPN epitaxial planar type

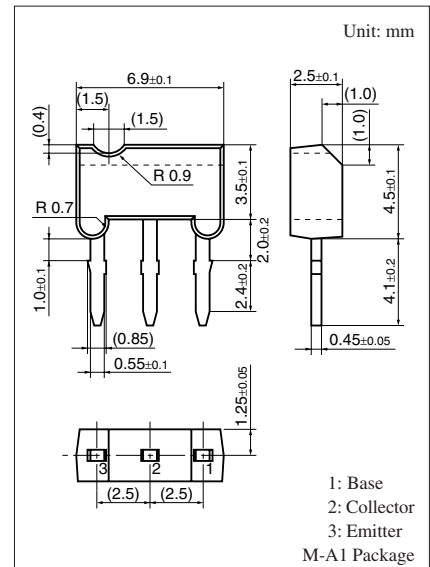
For high breakdown voltage general amplification

■ Features

- High collector-emitter voltage (Base open) V_{CEO}
- High transition frequency f_T
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	2SD0662	V_{CBO}	250	V
	2SD0662B		400	
Collector-emitter voltage (Base open)	2SD0662	V_{CEO}	200	V
	2SD0662B		400	
Emitter-base voltage (Collector open)	V_{EBO}	5	V	
Collector current	I_C	70	mA	
Collector power dissipation	P_C	600	mW	
Junction temperature	T_j	150	$^\circ\text{C}$	
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$	



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

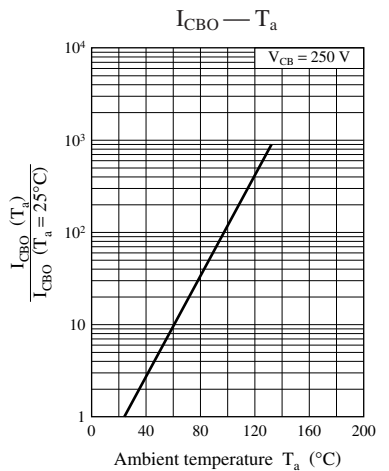
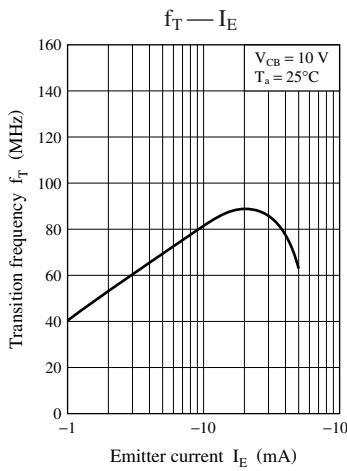
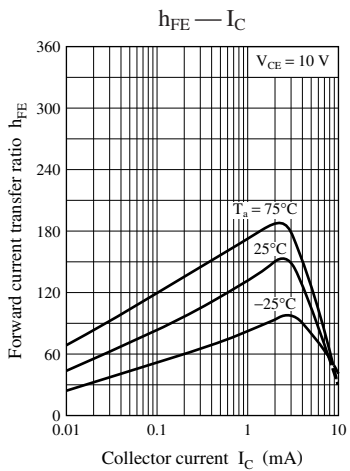
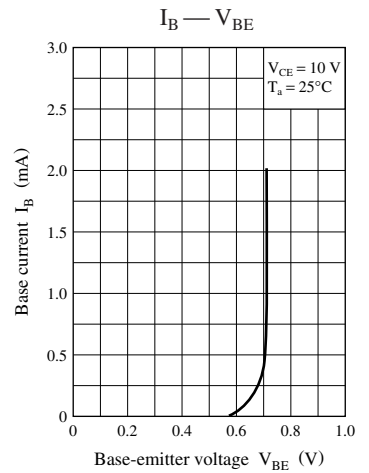
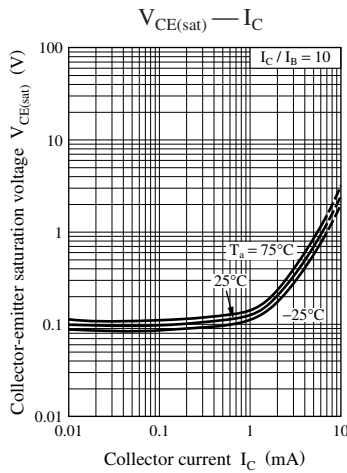
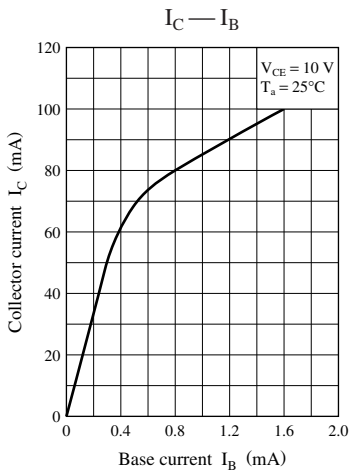
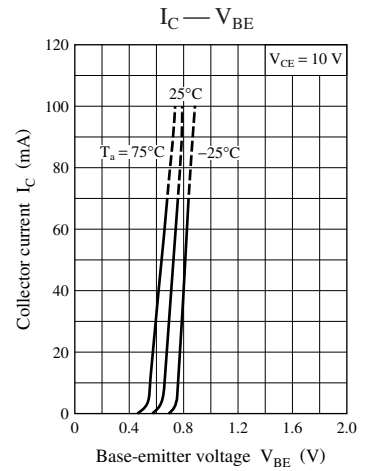
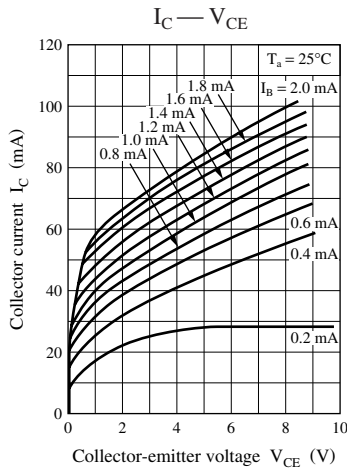
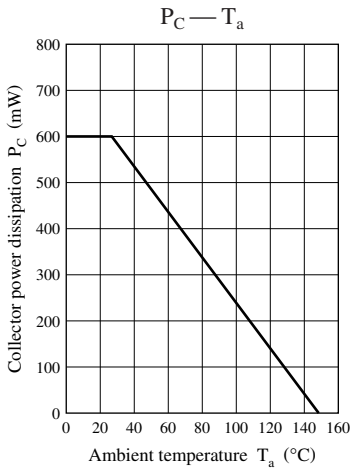
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	2SD0662	$I_C = 100 \mu\text{A}, I_B = 0$	200			V
	2SD0662B		400			
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu\text{A}, I_C = 0$	5			V
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 100 \text{V}, I_B = 0$			2	μA
Forward current transfer ratio	h_{FE}^*	$V_{CE} = 10 \text{V}, I_C = 5 \text{mA}$	30		220	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 50 \text{mA}, I_B = 5 \text{mA}$			1.2	V
Transition frequency	f_T	$V_{CB} = 10 \text{V}, I_E = -10 \text{mA}, f = 200 \text{MHz}$	50			MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = 10 \text{V}, I_E = 0, f = 1 \text{MHz}$			10	pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	P	Q	R
h_{FE}	30 to 100	60 to 150	100 to 220

Note) The part numbers in the parenthesis show conventional part number.



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